L Number	Hits	Search Text	DB	Time stamp
2	3759	438/595.ccls. 438/638.ccls. 438/639.ccls. 438/640.ccls.	USPAT; US-PGPUB	2004/10/18 09:51
	3	438/672.ccls. 438/675.ccls. 257/775.ccls. 6740916.pn. 6617631.pn. 6083788.pn.	USPAT;	2004/10/18 09:54
	3	0740916.pm. 0017031.pm. 0003700.pm.	US-PGPUB	2004/10/10 05.54
3	58	(438/595.ccls. 438/638.ccls. 438/639.ccls. 438/640.ccls.	USPAT;	2004/10/18 10:25
		438/672.ccls. 438/675.ccls. 257/775.ccls.) and ((gate wordline	US-PGPUB	,
		bitline ((word bit metal coduct\$6) adj (line trace runner		
		interconnect\$6))) same (hole opening via trench groove		
		window) same (contact plug stud land\$6 pad) same (taper\$6		
		funnel conical cone))		2004/40/40 40:20
4	559	((gate wordline bitline ((word bit metal coduct\$6) adj (line	USPAT;	2004/10/18 10:29
		trace runner interconnect\$6))) same (hole opening via trench groove window) same (contact plug stud land\$6 pad) same	US-PGPUB	
		(taper\$6 funnel conical cone)) and (semiconductor wafer	:	,
		silicon substrate)		
9	361	((hole opening via trench groove window) with (liner spacer	EPO; JPO;	2004/10/18 10:22
	55-	sidewall (side adj wall))) and (contact plug stud land\$6 pad)	DERWENT;	,,
		and (taper\$6 funnel conical cone (isotropic\$8 with etch\$6)) and	IBM_TDB	
		(semiconductor wafer silicon substrate)		
12	784	(((hole opening via trench groove window) with (liner spacer	USPAT;	2004/10/18 10:28
		sidewall (side adj wall))) same (contact plug stud land\$6 pad)	US-PGPUB	
		same (taper\$6 funnel conical cone)) and (semiconductor wafer		
10	110	silicon substrate)	USPAT;	2004/10/18 10:30
10	118	(438/595.ccls. 438/638.ccls. 438/639.ccls. 438/640.ccls. 438/672.ccls. 438/675.ccls. 257/775.ccls.) and ((gate wordline	US-PGPUB	2004/10/16 10:30
		bitline ((word bit metal coduct\$6) adj (line trace runner	03-7-07-05	
		interconnect\$6))) same (hole opening via trench groove		
		window) same (contact plug stud land\$6 pad) same (taper\$6		
		funnel conical cone (isotropic\$8 with etch\$6)))		
11	87	(438/595.ccls. 438/638.ccls. 438/639.ccls. 438/640.ccls.	USPAT;	2004/10/18 11:06
		438/672.ccls. 438/675.ccls. 257/775.ccls.) and (((hole opening	US-PGPUB	
		via trench groove window) with (liner spacer sidewall (side adj		
		wall))) same (contact plug stud land\$6 pad) same (taper\$6		
	444	funnel conical cone))	LICDATA	2004/10/10 11:40
13	111	((gate wordline bitline ((word bit metal coduct\$6) adj (line	USPAT; US-PGPUB	2004/10/18 11:40
		trace runner interconnect\$6))) same ((hole opening via trench groove window) with (liner spacer sidewall (side adj wall)))	03-19100	
		same (contact plug stud land\$6 pad) same (taper\$6 funnel		
		conical cone)) and (semiconductor wafer silicon substrate)		
7	204		EPO; JPO;	2004/10/18 12:07
		runner interconnect\$6))) and (hole opening via trench groove	DERWENT;	
		window) and (contact plug stud land\$6 pad) and (taper\$6	IBM_TDB	
		funnel conical cone) and (semiconductor wafer silicon		
		substrate)		2004/40/40 40 50
8	209	((hole opening via trench groove window) with (liner spacer	EPO; JPO;	2004/10/18 12:50
		sidewall (side adj wall))) and (contact plug stud land\$6 pad)	DERWENT;	
		and (taper\$6 funnel conical cone) and (semiconductor wafer silicon substrate)	IBM_TDB	
5	317	((gate wordline bitline ((word bit metal coduct\$6) adj (line	USPAT;	2004/10/18 14:12
5	21/	trace runner interconnect\$6))) same ((hole opening via trench	US-PGPUB	200 1/10/10 14.12
		groove window) with (taper\$6 funnel conical cone)) same		
		(contact plug stud land\$6 pad)) and (semiconductor wafer		
		silicon substrate)		